

#### Ceramic Plate Series Thermoelectric Cooler

The CP2-127-06-L2-W12 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 117.8 Watts when  $\Delta T = 0$  and a maximum  $\Delta T$  of 70.5 °C at Qc = 0.

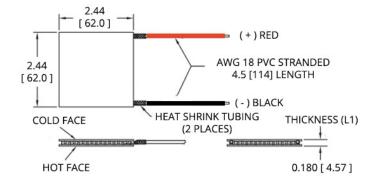
#### Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

#### Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision

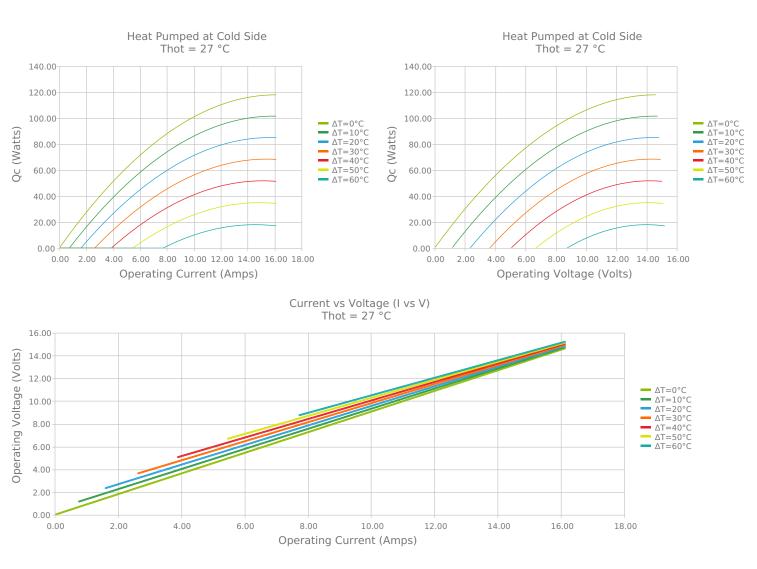


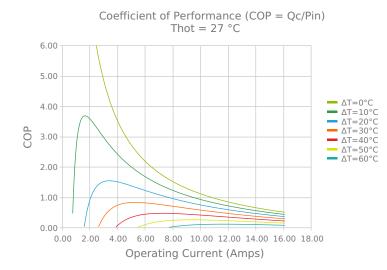


Ceramic Material: Alumina (Al<sub>2</sub>O<sub>3</sub>) Solder Construction: 138°C, Bismuth Tin (BiSn)

INCHES [ MM ]

#### **ELECTRICAL AND THERMAL PERFORMANCE**

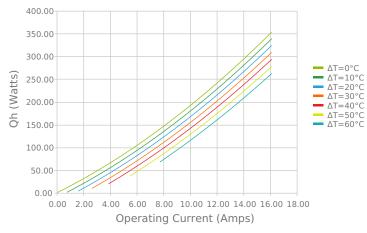


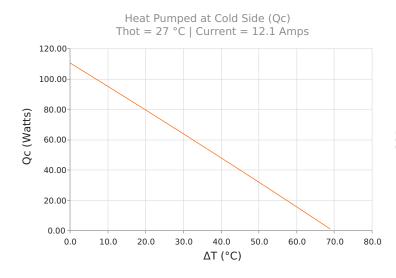


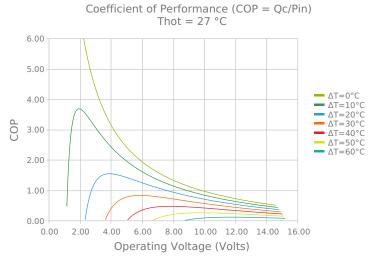
THERMAL

Laird

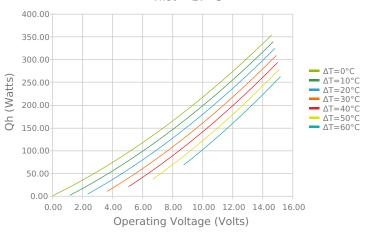




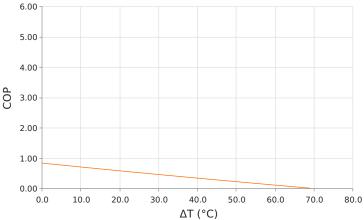




Total Heat Dissipated at Hot Side (Qh=Qc+Pin) Thot = 27  $^{\circ}C$ 



Coefficient of Performance (COP = Qc/Pin) Thot = 27 °C | Current = 12.1 Amps



## **SPECIFICATIONS\***

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	117.8 Watts	121.4 Watts	127.7 Watts
ΔTmax (Qc = 0)	70.5°C	73.5°C	78.8°C
lmax (I @ ΔTmax)	14.2 Amps	14.2 Amps	14.0 Amps
Vmax (V @ ΔTmax)	13.9 Volts	14.4 Volts	15.4 Volts
Module Resistance	0.91 Ohms	0.94 Ohms	1.02 Ohms
Max Operating Temperature	80 °C		
Weight	68.0 gram(s)		

\* Specifications reflect thermoelectric coefficients updated March 2020

## **FINISHING OPTIONS**

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length	
L2	4.572 ±0.013 mm 0.180 ± 0.001 in	0.013 mm / 0.013 mm 0.0005 in / 0.0005 in	Lapped	Lapped	114.3 mm 4.50 in	

## **SEALING OPTIONS**

Suffix	Sealant	Color	Temp Range	Description	
	None			No sealing specified	

# NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

Any information furnished by Laird and its agents, whether in specifications, data sheets, product catalogues or otherwise, is believed to be (but is not warranted as being) accurate and reliable, is provided for information only and does not form part of any contract with Laird. All specifications are subject to change without notice. Laird assumes no responsibility and disclaims all liability for losses or damages resulting from use of or reliance on this information. All Laird products are sold subject to the Laird Terms and Conditions of sale (including Laird's limited warranty) in effect from time to time, a copy of which will be furnished upon request.

© Copyright 2020 Laird Thermal Systems GmbH. All Rights Reserved. Laird, Laird Technologies, Laird Thermal Systems, the Laird Logo, and other word marks and logos are trademarks or registered trademarks of Laird Limited or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird or any third party intellectual property rights.

Date: 04/24/2020